# INTERNATIONAL STANDARD



Second edition 2003-10

# Packaging of components for automatic handling –

Part 5: Matrix trays

Emballage de composants pour opérations automatisées –

Partie 5: Supports matriciels

© IEC 2003 — Copyright - all rights reserved

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale International Electrotechnical Commission Международная Электротехническая Комиссия



For price, see current catalogue

U

# CONTENTS

FO	REWO	ORD 4		
1	Scop	9e 6		
2	Material			
	2.1	Electrostatic dissipative requirements		
	2.2	Effect of properties		
	2.3	Recycling and rigidity		
3	Mechanical stability			
	3.1	Loaded tray		
	3.2	Empty tray		
	3.3	Outer edges		
4	Tray	design, dimensions and other physical properties7		
	4.1	Tray design7		
		4.1.1 Number of pockets		
		4.1.2 Orientation of pockets		
		4.1.3 Design rules for pocket density		
	4.2	Overall tray dimensions		
	4.3	Cell dimensions		
	4.4	Tray vacuum pick-up sites10		
		4.4.1 Size		
		4.4.2 Centre		
		4.4.3 Perimeter		
	4.5	Detail features		
	4.6	Weight10		
	4.7	Movement of components10		
	4.8	Dimensional information11		
5	Pola	rity and orientation of components in the tray14		
	5.1	Pin one14		
	5.2	Loading14		
6	Tray	stacking14		
	6.1	Bundling14		
	6.2	Top protection14		
	6.3	Partial filling14		
	6.4	Protrusion of components		
	6.5	Stack-up14		
_	6.6	Damaging of components14		
7	Missing components			
8	Mark	ing15		

Figure 1– Sample of leaded packages	9
Figure 2 – Sample of grid array packages	9
Figure 3 – Tray main view	11
Figure 4 – Tray stacking details	12
Figure A.1 – Thin tray	17
Figure A.2 – Thick matrix	25
Table 1 – Height dimensions	8
Table A.1 – Variations	19
Table A.2 – PGA variations	27

# INTERNATIONAL ELECTROTECHNICAL COMMISSION

# PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING -

### Part 5: Matrix trays

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60286-5 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This second edition cancels and replaces the first edition published in 1995 and constitutes a technical revision.

This edition includes the following significant technical changes from the previous edition.

- a) The generic rules for the design of matrix trays are given in this standard. Newly developed trays which follow these rules will not be listed individually. Only those trays which conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.
- b) An update of the matrix trays, which do not conform to the design rules set forth herein, are considered as "non-standard trays" and are not preferred for use, is listed in Annex A.

The text of this standard is based on the following documents:

FDIS	Report on voting
40/1341/FDIS	40/1364/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

# PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING -

# Part 5: Matrix trays

#### 1 Scope

This part of IEC 60286 describes the common dimensions, tolerances and characteristics of the tray. It includes only those dimensions which are essential for the handling of the trays for the stated purpose and for placing or removing components from the trays.

Matrix trays are designed to facilitate the transport and handling of electronic components during their testing, baking, transport/storage, and final mounting by automatic placement equipment.

The generic rules for their design are given in this standard.. Newly developed trays which follow these rules will not be listed individually . Only those trays which conform to the design rules set forth herein are classified as "standard trays" and are thus preferred for use.

NOTE Matrix trays listed in Annex A which do not conform to the design rules set forth herein shall be considered as "non-standard trays" and are not preferred for use.

### 2 Material

#### 2.1 Electrostatic dissipative requirements

Trays shall be moulded from material that meets the ESD dissipative requirements which are: equal to, or greater than,  $1.0 \times 10^5$  ohms/square but less than  $1.0 \times 10^{12}$  ohms/square.

#### 2.2 Effect of properties

The tray material shall not adversely affect the mechanical, electrical characteristics, solderability, or marking of the component during or after transport, baking or storage in the tray.

#### 2.3 Recycling and rigidity

The tray material shall be reusable or recyclable and shall be rigid enough to avoid damage to the components during handling, loading, baking, testing, shipping and placement operations.

There should be space for a recycle logo and material code or material declaration close to 'Detail B'.

#### 3 Mechanical stability

#### 3.1 Loaded tray

Mechanical stability of loaded trays shall be such that the components are adequately retained, without lead damage, and can be easily removed from the tray.

#### 3.2 Empty tray

The empty tray shall withstand normal environmental conditions (including component baking temperatures, if required) without distorting, warping, expanding, shrinking or any other physical change outside the specified dimensions of the trays.